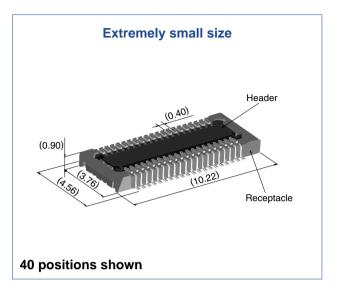
0.4 mm Pitch, 0.9 mm Height, Board-to-Board / Board-to-FPC Connectors

DF30 Series





Overview

Continuous miniaturization and increased component density on PCB created demand for extremely low profile connectors. This series is addition of a new extremely low profile connectors to Hirose's wide range of high reliability board-to-board/board-to-FPC connection solutions.

Features

1. Contact reliability

Concentration of the contact's normal forces at the single point assures good contact wipe and electrical reliability, while confirming the fully mated condition with a definite tactile click.

2. Self alignment

Recognizing the difficulties of mating extremely small connectors in limited spaces the connectors will self align in horizontal axis within 0.3 mm.

3. Automatic board placement

Packaged on tape-and-reel the plug and headers have sufficiently large flat areas to allow pick-up with vacuum nozzles of automatic placement equipment.

4. Variety of contact positions and styles

Available in standard contact positions of: 20, 22, 24, 30, 34, 40, 50, 60, 70 and 80 with and without metal fittings. Addition of metal fittings does not affect external dimensionsof the connectors.

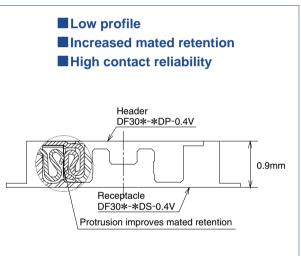
Smaller contact positions are also available.

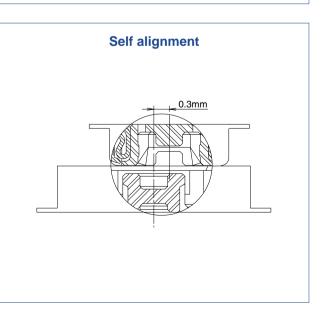
5. Support for continuity test connector

Connectors which have increased insertion and removal durability are available for continuity tests. Contact your Hirose sales representative for details.

Applications

Čellular phones, PDA's, mobile computers, digital cameras, digital video cameras, and other devices demanding high reliability connections in extremely limited spaces.





Product Specifications

	Rated current 0.3A	Operating temperature range	-35℃ to 85℃ (Note 1)	Storage temperature range	10°C to 60°C (Noto 2)
Rating	Rated voltage 30V AC	1 0 1 0	: Relative humidity 20% to 80%		()
	_			, , , , , , , , , , , , , , , , , , ,	,

Item	Specification	Conditions
1. Insulation resistance	50 MΩ min.	100V DC
2. Withstanding voltage	No flashover or insulation breakdown.	100V AC / one minute
3. Contact resistance	100 mΩ max.	100 mA
4. Vibration	No electrical discontinuity of 1 μ s or more	Frequency: 10 to 55 Hz, single amplitude of 0.75mm, 2 hours, 3 axis
5. Humidity	Contact resistance: 100 m Ω max. Insulation resistance: 25 M Ω min.	96 hours at temperature of $40^{\circ}C\pm 2^{\circ}C$ and RH of 90% to 95%
6. Temperature cycle	Contact resistance: 100 m Ω max. Insulation resistance: 50 M Ω min.	Temperature: -55 °C→ $+5$ °C to $+35$ °C→ $+85$ °C→ $+5$ °C to $+35$ °C Duration: 30 → 10 → 30 → 10 (Minutes) 5 cycles
7. Durability (insertions/withdrawals)	Contact resistance: 100 mΩ max.	50 cycles(Connector for conductivity tests: 500 cycles)
8. Resistance to soldering heat	No deformation of components affecting performance.	Reflow: At the recommended temperature profile Manual soldering: 300°C for 3 seconds

Note 1: Includes temperature rise caused by current flow.

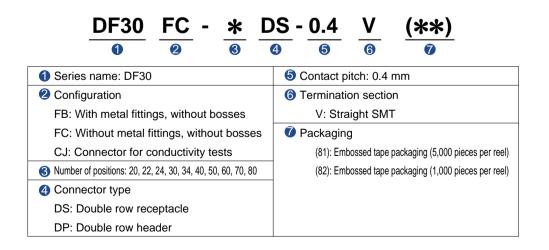
Note 2: The term "storage" refers to products stored for long period of time prior to mounting and use. Operating temperature range and humidity range covers non-conducting condition of installed connectors in storage, shipment or during transportation.

Materials and Finishes

Connectors	Component	Material	Finish	Remarks
Receptacles	Insulator	LCP	Color : Black	UL94V-0
and	Contacts	Phosphor bronze	Gold plated	
Headers	Metal fittings	Phosphor bronze	Tin-cupper plated	

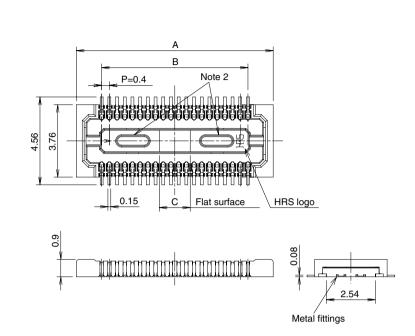
Ordering information

Receptacles and Headers

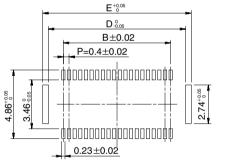


Receptacles (with metal fittings)





Recommended PCB mounting pattern



Recommended solder paste thickness: 120 μ m

[Specification number] -**, (**) (81): Embossed tape packaging (5,000 pieces per reel)

* Tolerances non- accumulative. Unit: mm							Unit: mm
Part Number	CL No.	Number of contacts	А	В	С	D	E
DF30FB-20DS-0.4V(**)	CL684-1098-3-**	20	6.22	3.6	1.2	5.72	6.52
DF30FB-22DS-0.4V(**)	CL684-1099-6-**	22	6.62	4.0	1.2	6.12	6.92
DF30FB-24DS-0.4V(**)	CL684-1100-3-**	24	7.02	4.4	1.2	6.52	7.32
DF30FB-30DS-0.4V(**)	CL684-1101-6-**	30	8.22	5.6	1.2	7.72	8.52
DF30FB-34DS-0.4V(**)	CL684-1102-9-**	34	9.02	6.4	1.36	8.52	9.32
DF30FB-40DS-0.4V(**)	CL684-1103-1-**	40	10.22	7.6	1.6	9.72	10.52
DF30FB-50DS-0.4V(**)	CL684-1104-4-**	50	12.22	9.6	2.0	11.72	12.52
DF30FB-60DS-0.4V(**)	CL684-1105-7-**	60	14.22	11.6	2.4	13.72	14.52
DF30FB-70DS-0.4V(**)	CL684-1106-0-**	70	16.22	13.6	2.8	15.72	16.52
DF30FB-80DS-0.4V(**)	CL684-1107-2-**	80	18.22	15.6	3.2	17.72	18.52

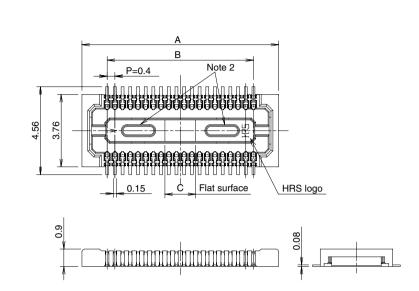
Note 1: Order by number of reels.

Note 2: Receptacles with 24 or fewer contacts positions will not have recessed areas.

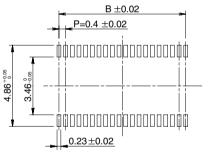
HS 3

Receptacles (without metal fittings)





Recommended PCB mounting pattern



Recommended solder paste thickness: 120 μm

(81): Embossed tape packaging (5,000 pieces per reel)

[Specification number] -**, (**)

Tolerances non- accumulative. Unit: mm						
Part Number	CL No.	Number of contacts	А	В	C	
DF30FC-20DS-0.4V(**)	CL684-1109-8-**	20	6.22	3.6	1.2	
DF30FC-22DS-0.4V(**)	CL684-1110-7-**	22	6.62	4.0	1.2	
DF30FC-24DS-0.4V(**)	CL684-1111-0-**	24	7.02	4.4	1.2	
DF30FC-30DS-0.4V(**)	CL684-1112-2-**	30	8.22	5.6	1.2	
DF30FC-34DS-0.4V(**)	CL684-1113-5-**	34	9.02	6.4	1.36	
DF30FC-40DS-0.4V(**)	CL684-1078-6-**	40	10.22	7.6	1.6	
DF30FC-50DS-0.4V(**)	CL684-1114-8-**	50	12.22	9.6	2.0	
DF30FC-60DS-0.4V(**)	CL684-1082-3-**	60	14.22	11.6	2.4	
DF30FC-70DS-0.4V(**)	CL684-1115-0-**	70	16.22	13.6	2.8	
DF30FC-80DS-0.4V(**)	CL684-1116-3-**	80	18.22	15.6	3.2	

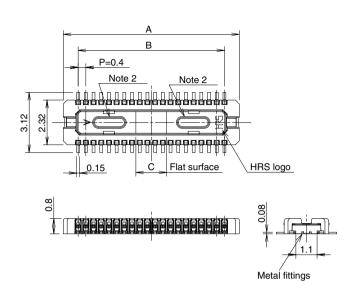
Note 1: Order by number of reels.

Note 2: Receptacles with 24 or fewer contacts positions will not have recessed areas.

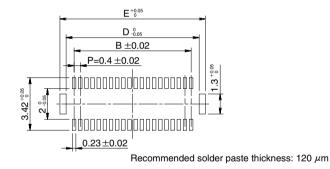
4	HRS
4	

Header (with metal fittings)





Recommended PCB mounting pattern



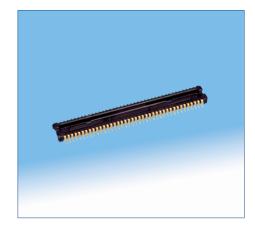
[Specification number] -**, (**) (81): Embossed tape packaging (5,000 pieces per reel)

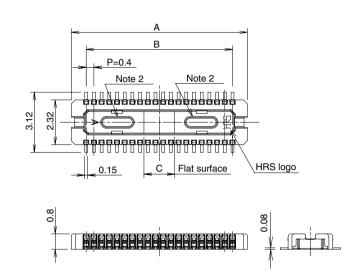
Tolerances non- accumulative. Unit: mm							
Part Number	CL No.	Number of contacts	А	В	С	D	E
DF30FB-20DP-0.4V(**)	CL684-1129-5-**	20	5.14	3.6	1.2	4.64	5.44
DF30FB-22DP-0.4V(**)	CL684-1130-4-**	22	5.54	4.0	1.2	5.04	5.84
DF30FB-24DP-0.4V(**)	CL684-1131-7-**	24	5.94	4.4	1.2	5.44	6.24
DF30FB-30DP-0.4V(**)	CL684-1132-0-**	30	7.14	5.6	1.2	6.64	7.44
DF30FB-34DP-0.4V(**)	CL684-1133-2-**	34	7.94	6.4	1.36	7.44	8.24
DF30FB-40DP-0.4V(**)	CL684-1134-5-**	40	9.14	7.6	1.6	8.64	9.44
DF30FB-50DP-0.4V(**)	CL684-1135-8-**	50	11.14	9.6	2.0	10.64	11.44
DF30FB-60DP-0.4V(**)	CL684-1074-5-**	60	13.14	11.6	2.4	12.64	13.44
DF30FB-70DP-0.4V(**)	CL684-1075-8-**	70	15.14	13.6	2.8	14.64	15.44
DF30FB-80DP-0.4V(**)	CL684-1136-0-**	80	17.14	15.6	3.2	16.64	17.44

Note 1: Order by number of reels.

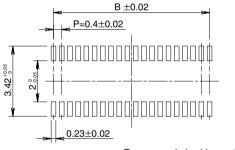
Note 2: Headers with 24 or fewer contacts positions will not have protruding areas.

Header (without metal fittings)





Recommended PCB mounting pattern



Recommended solder paste thickness: 120 μ m

(81): Embossed tape packaging (5,000 pieces per reel)

[Specification number] -**, (**)

* Tolerances non- accumul	Tolerances non- accumulative. Unit: mm						
Part Number	CL No.	Number of contacts	A	В	C		
DF30FC-20DP-0.4V(**)	CL684-1138-6-**	20	5.14	3.6	1.2		
DF30FC-22DP-0.4V(**)	CL684-1139-9-**	22	5.54	4.0	1.2		
DF30FC-24DP-0.4V(**)	CL684-1140-8-**	24	5.94	4.4	1.2		
DF30FC-30DP-0.4V(**)	CL684-1141-0-**	30	7.14	5.6	1.2		
DF30FC-34DP-0.4V(**)	CL684-1142-3-**	34	7.94	6.4	1.36		
DF30FC-40DP-0.4V(**)	CL684-1079-9-**	40	9.14	7.6	1.6		
DF30FC-50DP-0.4V(**)	CL684-1143-6-**	50	11.14	9.6	2.0		
DF30FC-60DP-0.4V(**)	CL684-1083-6-**	60	13.14	11.6	2.4		
DF30FC-70DP-0.4V(**)	CL684-1077-3-**	70	15.14	13.6	2.8		
DF30FC-80DP-0.4V(**)	CL684-1144-9-**	80	17.14	15.6	3.2		

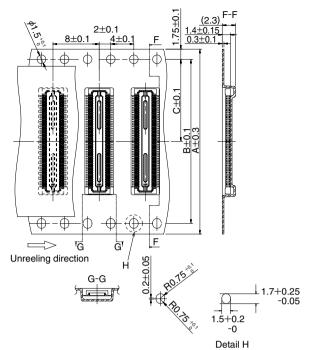
Note 1: Order by number of reels.

Note 2: Headers with 24 or fewer contacts positions will not have protruding areas.

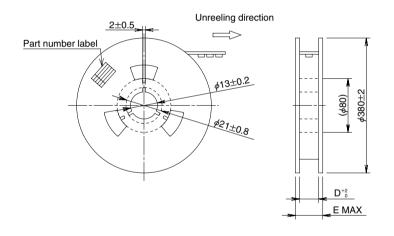
6	HS
-	

Packaging Specification

• Embossed Carrier Tape Dimensions - Receptacle



Reel Dimensions

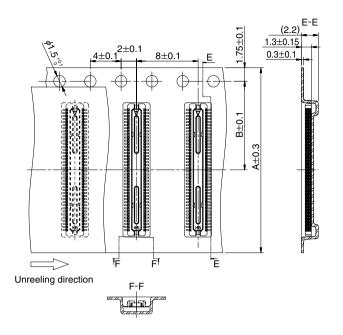


Unit: mm	U	nit:	mm
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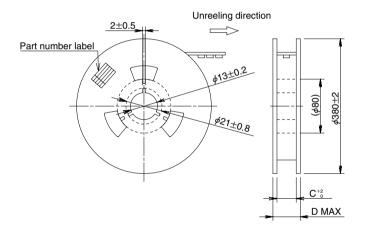
					Unit: mm
Part Number	А	В	С	D	E
DF30#-20DS-0.4V(**)	16.0	-	7.5	16.4	22.4
DF30#-22DS-0.4V(**)	16.0	-	7.5	16.4	22.4
DF30#-24DS-0.4V(**)	16.0	-	7.5	16.4	22.4
DF30#-30DS-0.4V(**)	16.0	-	7.5	16.4	22.4
DF30#-34DS-0.4V(**)	16.0	-	7.5	16.4	22.4
DF30#-40DS-0.4V(**)	24.0	-	11.5	24.4	30.4
DF30#-50DS-0.4V(**)	24.0	-	11.5	24.4	30.4
DF30#-60DS-0.4V(**)	24.0	-	11.5	24.4	30.4
DF30#-70DS-0.4V(**)	24.0	-	11.5	24.4	30.4
DF30#-80DS-0.4V(**)	32.0	28.4	14.2	32.4	38.4
		1	1	1	1

Embossed tape 32mm or wider will have perforated feed holes on two sides.

• Embossed Carrier Tape Dimensions - Header



Reel Dimensions

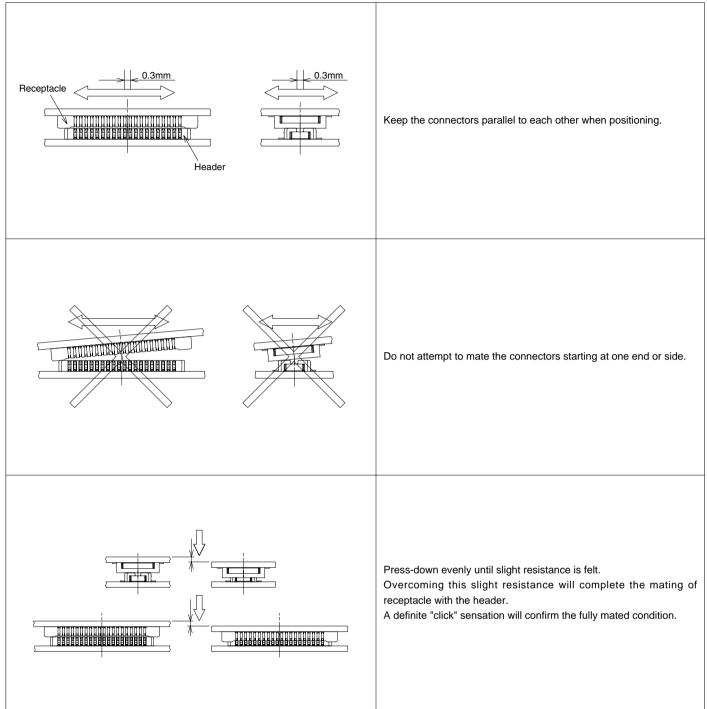


				Unit: mm
Part Number	А	В	С	D
DF30#-20DP-0.4V(**)	16.0	7.5	16.4	22.4
DF30#-22DP-0.4V(**)	16.0	7.5	16.4	22.4
DF30#-24DP-0.4V(**)	16.0	7.5	16.4	22.4
DF30#-30DP-0.4V(**)	16.0	7.5	16.4	22.4
DF30#-34DP-0.4V(**)	16.0	7.5	16.4	22.4
DF30#-40DP-0.4V(**)	16.0	7.5	16.4	22.4
DF30#-50DP-0.4V(**)	24.0	11.5	24.4	30.4
DF30#-60DP-0.4V(**)	24.0	11.5	24.4	30.4
DF30#-70DP-0.4V(**)	24.0	11.5	24.4	30.4
DF30#-80DP-0.4V(**)	24.0	11.5	24.4	30.4

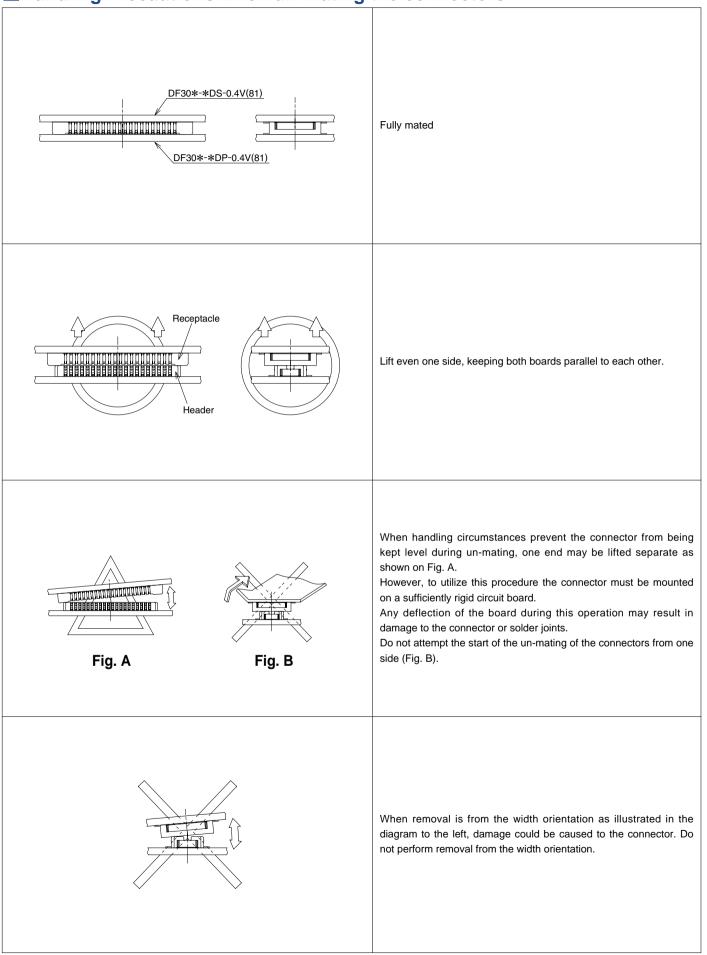
Usage Recommendations

1. Recommended temperature profile	
	(Temperature) 250°C 250°C 250°C 250°C 250°C 250°C 20°C 20°C 50°C 10°C 50°C 10°C 50°C 0 sec. max. 220°C 60 sec. max. 220°C 60 sec. max. 220°C 60 sec. max. 220°C 60 sec. max. 220°C 60 sec. max. 50°C 60 sec. max. 50°C 0 sec. 50 sec. 100 sec. 150 sec. (Time) Note 1: Up to 2 cycles of Reflow soldering are possible under the same conditions, provided that there is a return to normal temperature between the first and second cycle. Note 2: The temperature profile indicates the board surface temperature at the point of contacts with the connector terminals.
2. Recommended manual soldering	Manual soldering: 290±10°C for 3 seconds
3. Recommended screen thickness and	Thickness: 0.12 mm
open area ratio (Pattern area ratio)	Opening are ratio: DS side 100%, DP side 84%
4.Board warpage	Maximum of 0.02 mm at the connector center, with both ends of the connector as reference points.
5.Cleaning conditions	Refer to "Nylon Connector Use Handbook".
6. Precautions	 Due to the extremely small size of the connectors, handling it with bare hands should be avoided. Follow the recommendations given on the proceeding pages. Use of fluxes is NOT recommended.
	Different production lots may exhibit some discoloration of the insulator material. This
	will not affect form, fit or function of the connectors.
	The connectors should not be used a sole PCB support. It is recommended to use
	additional means of board support.

Handling Precautions when mating the connectors



● Handling Precautions when un-mating the connectors



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